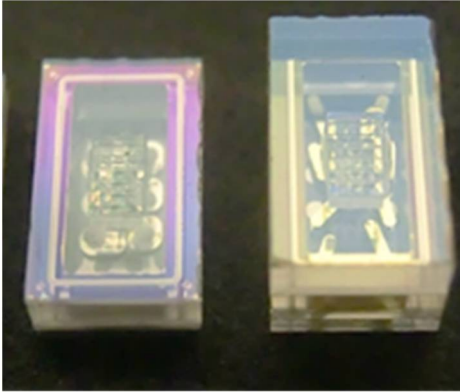




Webinar 3

Packaging of miniature optical components



“Miniaturization and hybrid integration are key in further development of highly integrated and cost-effective microsystems. Especially, in the photonic packaging where many miniature components need to be assembled with high precision, novel techniques for alignment, bonding and hermetic sealing are required. Here, we are presenting challenges and assembly techniques used for integration of laser chips to other miniature optical components.”

Rony Jose James, MSc. is Project Manager at CSEM SA, Switzerland. He is working at CSEM since 2007, focusing on integration of microsystems. He received his Master's degree in Micro and Nano-Technology from Helsinki University of Technology in 2006. He has more than 16 years of experience in development of microsystem packaging technologies, focusing on topics like hermetic sealing and feedthrough technologies for micro-implantable devices, fine pitch bonding technologies, reliability analysis, photonic packaging and hybrid integration. He is the current chairman of the IEEE Electronic packaging Society, Swiss chapter.



Join Rony's talk on Wednesday, May 11 at 11am CET, on the Zoom-link below

